

A B S T R A C T

A thermosetting resin composition capable of providing
a molding, such as a resin sheet, that excels in not only dielectric
5 characteristics but also dimensional stability at high
temperature and even after exposure to high temperature thermal
history, exhibits little dimensional change by the thermal
history, namely, exhibiting low linear expansion coefficient.
There are further provided a resin sheet and resin sheet for
10 insulated substrate produced from the thermosetting resin
composition. In particular, there is provided a thermosetting
resin composition comprising an epoxy resin of 100 to 2000 epoxy
equivalent, an epoxy resin hardening agent consisting of a
phenolated compound, and a layered silicate, and are further
15 provided a resin sheet comprised of the thermosetting resin
composition and a resin sheet for insulated substrate comprised
of the resin sheet.